

- Designed for 802.11 Applications
- · Hermetically sealed Surface Mount package
- Complies with Directive 2002/95/EC (RoHS)

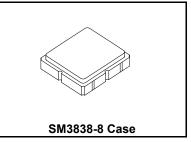


#### **Absolute Maximum Ratings**

Rating	Value	Units
Maximum Input Power	+10	dBm
DC Voltage Between Terminals	30	VDC
Case Temperature	-40 to +85	°C
Suitable for lead-free soldering - Max Soldering Profile	260°C for 30 s	

### **SF1174D**

## 374.00 MHz **SAW Filter**

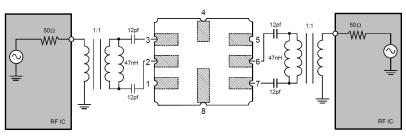


#### **Electrical Characteristics**

Characteristic		Sym	Notes	Minimum	Typical	Maximu	Units
Nominal Operating Freque	ncy	f <sub>C</sub>			374		MHz
Passband	Insertion Loss	IL			8.6	10	dB
	3.0 dB Bandwidth			17	23.3		MHz
Amplitude Ripple	Fc ±7 MHz				.6	1.0	dB
Group Delay Deviation	Fc ±7 MHz				45	100	nsec
Rejection	Fc-100 to -33 MHz			40	47		dB
	Fc-33 to -22 MHz			40	48		dB
	Fc-22 to -16.5 MHz			27	40		dB
	Fc+16.5 to +22 MHz			28	44		dB
	Fc+22 to +43 MHz			35	44		dB
	Fc+43 to +80 MHz			40	45		dB
Ambient Temperature	Operating Range			-20		70	°C
Footprint Size: 3.8 X 3.8			I	SM	13838-8	1	I
Lid Symbolization (Y=Year	, WW=week, S=shift)	L		479	// YWWS		

#### **Electrical Connections**

Connection	Terminals
Differential Input	2, 3
Differential Output	6, 7
Ground	All Others





CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

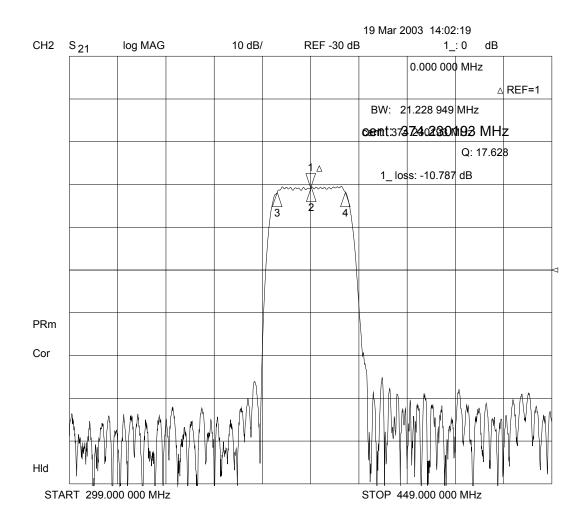
#### NOTES:

- All specifications apply over the operating temperature range with filter soldered to the specified demonstration board unless noted otherwise. Ultimate rejection is dependent on PCB layout.
- Specifications subject to change without notice.
  Electrostatic Sensitive Device. Observe precautions for handling.
- 5. 6.
- US and international patents may apply.

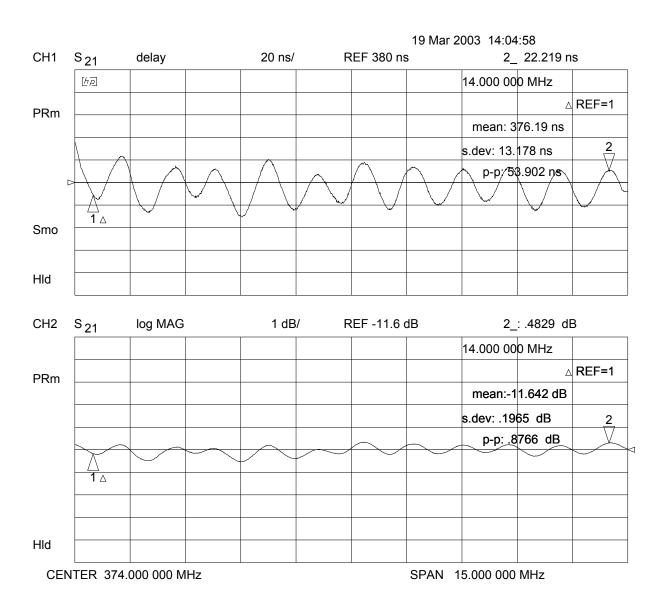
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#### SF1174D-Demo Reference Plot

1dB per transformer insertion loss is not calibrated out

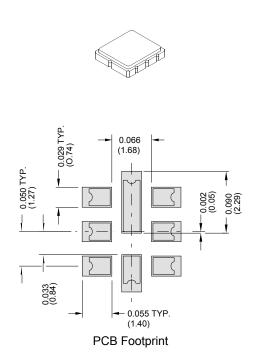


#### SF1174D-Demo Reference Plot



## **SM3838-8 Case**

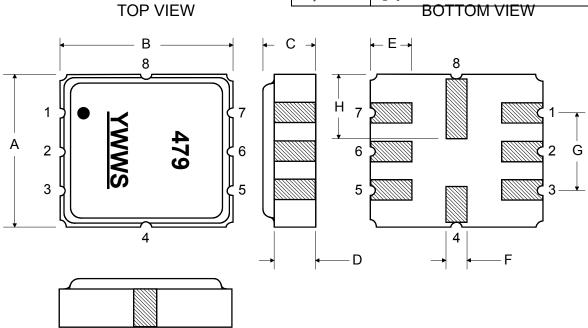
# 8-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint



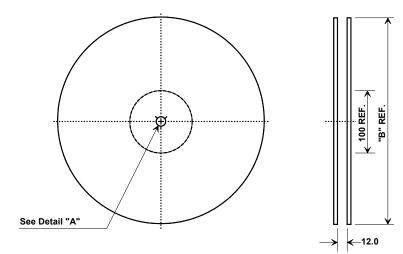
Case Dimensions						
Dimension	mm		Inches			
	Min	Nom	Max	Min	Nom	Max
Α	3.6	3.8	4.0		0.15	
В	3.6	3.8	4.0		0.15	
С			1.25		0.06	
D		1.0			0.04	
E		1.0			0.04	
F		0.6			0.02	
G	2.39	2.54	2.69		0.100	
Н		1.5			0.06	

Electrical Connections				
	Connection	Terminals		
Port 1	Differential Input	2, 3		
Port 2	Differential Output	6, 7		
Ground		All Others		
Single Ended C	Return is Ground			
Differential Operation		Return is Hot		
Dot Indicates Pin 1				

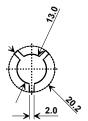
Materials				
Solder Pad Ter- mination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.			
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			



#### **Tape and Reel Specifications**



"B " Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



#### **COMPONENT ORIENTATION and DIMENSIONS**

Carrier Tape Dimensions			
Ao	4.25 mm		
Во	4.25 mm		
Ko	1.30 mm		
Pitch	8.0 mm		
W	12.0 mm		

